

June 2008

### NC7SV04

# TinyLogic® ULP-A Inverter

#### **Features**

- 0.9V to 3.6V V<sub>CC</sub> supply operation
- 3.6V overvoltage tolerant I/O's at V<sub>CC</sub> from 0.9V to 3.6V
- Extremely High Speed t<sub>PD</sub>:
  - 1.5ns typ. for 2.7V to 3.6V V<sub>CC</sub>
  - 1.8ns typ. for 2.3V to 2.7V  $V_{CC}$
  - 2.0ns typ. for 1.65V to 1.95V V<sub>CC</sub>
  - 3.2ns typ. for 1.4V to 1.6V  $V_{CC}$
  - 6.0ns typ. for 1.1V to 1.3V  $V_{CC}$
  - 12ns typ. for 0.9V V<sub>CC</sub>
- Power-Off high impedance inputs and outputs
- High Static Drive (I<sub>OH</sub>/I<sub>OL</sub>):
  - ±24mA @ 3.00V V<sub>CC</sub>
  - ±18mA @ 2.30V V<sub>CC</sub>
  - ±6mA @ 1.65V V<sub>CC</sub>
  - ±4mA @ 1.4V V<sub>CC</sub>
  - ±2mA @ 1.1V V<sub>CC</sub>
  - ±0.1mA @ 0.9V V<sub>CC</sub>
- Uses patented Quiet Series<sup>™</sup> noise/EMI reduction circuitry
- Ultra small MicroPak<sup>™</sup> package
- Ultra low dynamic power

#### **General Description**

The NC7SV04 is a single inverter from Fairchild's Ultra Low Power-A (ULP-A) Series of TinyLogic®. ULP-A is ideal for applications that require extreme high speed, high drive and low power. This product is designed for a wide low voltage operating range (0.9V to 3.6V V<sub>CC</sub>) and applications that require more drive and speed than the TinyLogic ULP series, but still offer best in class low power operation.

The NC7SV04 is uniquely designed for optimized power and speed, and is fabricated with an advanced CMOS technology to achieve high-speed operation while maintaining low CMOS power dissipation.

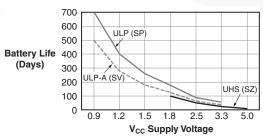
# **Ordering Information**

Order Number	Package Number	Package Code Top Mark	Package Description	Supplied As
NC7SV04P5X	MAA05A	V04	5-Lead SC70, EIAJ SC-88a, 1.25mm Wide	3k Units on Tape and Reel
NC7SV04L6X	MAC06A	F7	6-Lead MicroPak, 1.0mm Wide	5k Units on Tape and Reel



All packages are lead free per JEDEC: J-STD-020B standard.

# Battery Life vs. V<sub>CC</sub> Supply Voltage



TinyLogic ULP and ULP-A with up to 50% less power consumption can extend your battery life significantly.

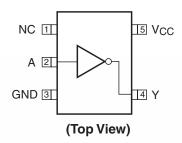
Battery Life = (V<sub>battery</sub> x I<sub>battery</sub> x 0.9) / (P<sub>device</sub>) / 24hrs/day

Where,  $P_{device} = (I_{CC} \times V_{CC}) + (C_{PD} + C_L) \times V_{CC}^2 \times f$ 

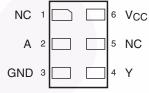
Assumes ideal 3.6V Lithium Ion battery with current rating of 900mAH and derated 90% and device frequency at 10MHz, with  $C_L = 15pF$  load.

### **Connection Diagrams**

### Pin Assignment for SC70



#### Pad Assignments for MicroPak



(Top Through View)

# **Logic Symbol**



#### **Function Table**

 $Y = \overline{A}$ 

Input	Output
Α	Υ
L	Н
Н	L

H = HIGH Logic Level

L = LOW Logic Level

# **Pin Description**

Pin Name	Description
А	Input
Y	Output
NC	No Connect

#### **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V <sub>CC</sub>	Supply Voltage	-0.5V to +4.6V
V <sub>IN</sub>	DC Input Voltage	-0.5V to +4.6V
V <sub>OUT</sub>	DC Output Voltage HIGH or LOW State <sup>(1)</sup> V <sub>CC</sub> = 0V	-0.5V to V <sub>CC</sub> +0.5V -0.5V to +4.6V
I <sub>IK</sub>	DC Input Diode Current @ V <sub>IN</sub> < 0V	-50mA
I <sub>OK</sub>	DC Output Diode Current	
	V <sub>OUT</sub> < 0V	-50mA
	V <sub>OUT</sub> > V <sub>CC</sub>	+50mA
I <sub>OH</sub> /I <sub>OL</sub>	DC Output Source/Sink Current	±50mA
I <sub>CC</sub> or Ground	DC V <sub>CC</sub> or Ground Current per Supply Pin	±50mA
T <sub>STG</sub>	Storage Temperature Range	-65°C to +150°C
TJ	Junction Temperature Under Bias	150°C
T <sub>L</sub>	Junction Lead Temperature (Soldering, 10 seconds)	260°C
P <sub>D</sub>	Power Dissipation @ +85°C	
	SC70-5	150mW
	Micropak-6	130mW

# Recommended Operating Conditions<sup>(2)</sup>

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
V <sub>CC</sub>	Supply Voltage	0.9V to 3.6V
V <sub>IN</sub>	Input Voltage	0V to 3.6V
V <sub>OUT</sub>	Output Voltage	
	HIGH or LOW State	0V to V <sub>CC</sub>
	$V_{CC} = 0V$	0V to 3.6V
I <sub>OH</sub> /I <sub>OL</sub>	Output Current in I <sub>OH</sub> /I <sub>OL</sub>	
	$V_{CC} = 3.0V \text{ to } 3.6V$	±24mA
	$V_{CC} = 2.3V \text{ to } 2.7V$	±18mA
	$V_{CC} = 1.65V$ to 1.95V	±6mA
	$V_{CC} = 1.4V \text{ to } 1.6V$	±4mA
	$V_{CC} = 1.1V \text{ to } 1.3V$	±2mA
	$V_{CC} = 0.9V$	±0.1mA
T <sub>A</sub>	Free Air Operating Temperature	-40°C to +85°C
Δt/ΔV	Minimum Input Edge Rate @ V <sub>IN</sub> = 0.8V to 2.0V, V <sub>CC</sub> = 3.0V	10ns/V
$\theta_{JA}$	Thermal Resistance	
	SC70-5	425°C/W
	Micropak-6	500°C/W

#### Notes:

- 1. IO Absolute Maximum Rating must be observed.
- 2. Unused inputs must be held HIGH or LOW. They may not float.

# **DC Electrical Characteristics**

					T	_ =		
		Parameter V <sub>CC</sub> (V)		+2	5°C	-40°C t	o +85°C	
Symbol	Parameter		Conditions	Min.	Max.	Min.	Max.	Units
V <sub>IH</sub>	HIGH Level	0.90		0.65 x V <sub>CC</sub>		0.65 x V <sub>CC</sub>		V
	Input Voltage	1.10 ≤ V <sub>CC</sub> ≤ 1.30		0.65 x V <sub>CC</sub>		0.65 x V <sub>CC</sub>		1
		1.40 ≤ V <sub>CC</sub> ≤ 1.60		0.65 x V <sub>CC</sub>		0.65 x V <sub>CC</sub>		1
		1.65 ≤ V <sub>CC</sub> ≤ 1.95		0.65 x V <sub>CC</sub>		0.65 x V <sub>CC</sub>		1
		2.30 ≤ V <sub>CC</sub> < 2.70		1.6		1.6		1
		2.70 ≤ V <sub>CC</sub> ≤ 3.60		2.0		2.0		1
$V_{IL}$	LOW Level	0.90			0.35 x V <sub>CC</sub>		0.35 x V <sub>CC</sub>	V
	Input Voltage	1.10 ≤ V <sub>CC</sub> ≤ 1.30			0.35 x V <sub>CC</sub>		0.35 x V <sub>CC</sub>	1
		1.40 ≤ V <sub>CC</sub> ≤ 1.60			0.35 x V <sub>CC</sub>		0.35 x V <sub>CC</sub>	1
		1.65 ≤ V <sub>CC</sub> ≤ 1.95			0.35 x V <sub>CC</sub>		0.35 x V <sub>CC</sub>	1
		2.30 ≤ V <sub>CC</sub> < 2.70			0.7		0.7	1
		$2.70 \le V_{CC} \le 3.60$			0.8		0.8	1
V <sub>OH</sub>	HIGH Level	0.90	$I_{OH} = -100 \mu A$	V <sub>CC</sub> - 0.1		V <sub>CC</sub> - 0.1		V
	Output Voltage	1.10 ≤ V <sub>CC</sub> ≤ 1.30		V <sub>CC</sub> - 0.1		V <sub>CC</sub> - 0.1		1
		1.40 ≤ V <sub>CC</sub> ≤ 1.60		V <sub>CC</sub> - 0.2		V <sub>CC</sub> - 0.2		
		1.65 ≤ V <sub>CC</sub> ≤ 1.95		V <sub>CC</sub> - 0.2		V <sub>CC</sub> - 0.2		
		2.30 ≤ V <sub>CC</sub> < 2.70		V <sub>CC</sub> - 0.2		V <sub>CC</sub> - 0.2		
		2.70 ≤ V <sub>CC</sub> ≤ 3.60		V <sub>CC</sub> - 0.2		V <sub>CC</sub> - 0.2		
		1.10 ≤ V <sub>CC</sub> ≤ 1.30	$I_{OH} = -2mA$	0.75 x V <sub>CC</sub>		0.75 x V <sub>CC</sub>		
		1.40 ≤ V <sub>CC</sub> ≤ 1.60	$I_{OH} = -4mA$	0.75 x V <sub>CC</sub>		0.75 x V <sub>CC</sub>		1
		1.65 ≤ V <sub>CC</sub> ≤ 1.95	$I_{OH} = -6mA$	1.25		1.25		
		2.30 ≤ V <sub>CC</sub> < 2.70		2.0		2.0		
		2.30 ≤ V <sub>CC</sub> < 2.70	$I_{OH} = -12mA$	1.8		1.8		
		2.70 ≤ V <sub>CC</sub> ≤ 3.60		2.2		2.2		
		2.30 ≤ V <sub>CC</sub> < 2.70	$I_{OH} = -18mA$	1.7		1.7		1
		2.70 ≤ V <sub>CC</sub> ≤ 3.60		2.4		2.4		
		2.70 ≤ V <sub>CC</sub> ≤ 3.60	$I_{OH} = -24mA$	2.2		2.2		1
V <sub>OL</sub>	LOW Level	0.90	I <sub>OL</sub> = 100μA		0.1		0.1	V
	Output Voltage	1.10 ≤ V <sub>CC</sub> ≤ 1.30			0.1		0.1	1
		$1.40 \le V_{CC} \le 1.60$			0.2		0.2	1
		1.65 ≤ V <sub>CC</sub> ≤ 1.95			0.2		0.2	1
		2.30 ≤ V <sub>CC</sub> < 2.70			0.2		0.2	
		2.70 ≤ V <sub>CC</sub> ≤ 3.60			0.2		0.2	
		1.10 ≤ V <sub>CC</sub> ≤ 1.30	I <sub>OL</sub> = 2mA		0.25 x V <sub>CC</sub>		0.25 x V <sub>CC</sub>	
		1.40 ≤ V <sub>CC</sub> ≤ 1.60	I <sub>OL</sub> = 4mA		0.25 x V <sub>CC</sub>		0.25 x V <sub>CC</sub>	
		1.65 ≤ V <sub>CC</sub> ≤ 1.95	I <sub>OL</sub> = 6mA		0.3		0.3	
		$2.30 \le V_{CC} < 2.70$	I <sub>OL</sub> = 12mA		0.4		0.4	1
		$2.70 \le V_{CC} \le 3.60$	1		0.4		0.4	1
		2.30 ≤ V <sub>CC</sub> < 2.70	I <sub>OL</sub> = 18mA		0.6		0.6	1
		$2.70 \le V_{CC} \le 3.60$	1		0.4		0.4	1
		2.70 ≤ V <sub>CC</sub> ≤ 3.60	I <sub>OL</sub> = 24mA		0.55		0.55	1

# DC Electrical Characteristics (Continued)

				<b>T</b> <sub>A</sub> =				
				+2	5°C	-40°C to +85°C		
Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	Min.	Max.	Min.	Max.	Units
I <sub>IN</sub>	Input Leakage Current	0.90 to 3.60	$0 \le V_I \le 3.6V$		±0.1		±0.5	μA
I <sub>OFF</sub>	Power Off Leakage Current	0	$0 \le (V_I, V_O) \le 3.6V$		0.5		0.5	μA
I <sub>CC</sub>	Quiescent	0.90 to 3.60	$V_I = V_{CC}$ or GND		0.9		0.9	μA
	Supply Current		$V_{CC} \le V_I \le 3.6V$				±0.9	

# **AC Electrical Characteristics**

			T <sub>A</sub> =							
					-40°C to +25°C +85°C				Figure	
Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	Min.	Тур.	Max.	Min.	Max.	Units	
t <sub>PHL</sub> , t <sub>PLH</sub>	Propagation Delay	0.90	$C_L = 15pF,$ $R_L = 1M\Omega$		12				ns	Figure 1 Figure 2
	1.10 ≤ V <sub>CC</sub> ≤ 1.30		$C_L = 15pF$ ,	2.0	6	9.0	1.0	13.9		
		$1.40 \le V_{CC} \le 1.60$	$R_L = 2k\Omega$	1.0	3.2	5.1	0.9	6.0		
		$1.65 \le V_{CC} \le 1.95$		1.0	2.0	4.2	0.7	5.2		
		$2.30 \le V_{CC} < 2.70$	$R_L = 500\Omega$	0.8	1.8	2.7	0.6	3.4		
		$2.70 \le V_{CC} \le 3.60$		0.7	1.5	2.3	0.5	2.8		
C <sub>IN</sub>	Input Capacitance	0			2.0				pF	
C <sub>PD</sub>	Power Dissipation Capacitance	0.90 to 3.60	$V_I = 0V \text{ or } V_{CC},$ f = 10  MHz		10				pF	

# **AC Loading and Waveforms**

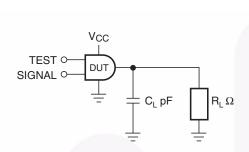


Figure 1. AC Test Circuit

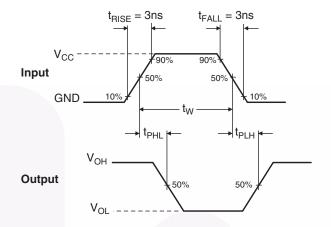


Figure 2. AC Waveforms

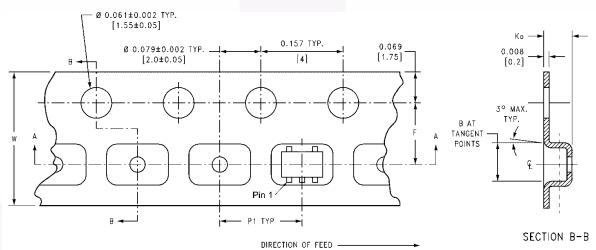
	V <sub>cc</sub>								
Symbol	3.3V ± 0.3V	2.5V ± 0.2V	1.8V ± 0.15V	1.5V ± 0.1V	1.2V ± 0.1V	0.9V			
V <sub>mi</sub>	1.5V	V <sub>CC</sub> /2							
V <sub>mo</sub>	1.5V	V <sub>CC</sub> /2							

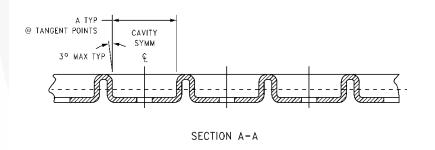
# **Tape and Reel Specification**

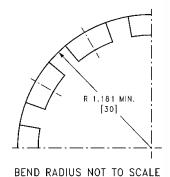
### **Tape Format for SC70**

Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status	
P5X	Leader (Start End)	125 (typ.)	Empty	Sealed	
	Carrier	3000	Filled	Sealed	
	Trailer (Hub End)	75 (typ.)	Empty	Sealed	

#### Tape Dimension inches (millimeters)





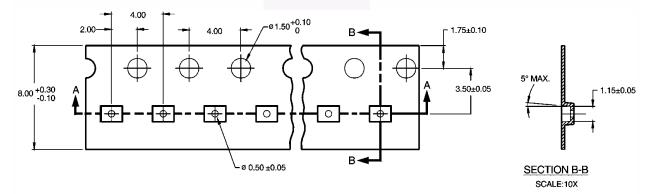


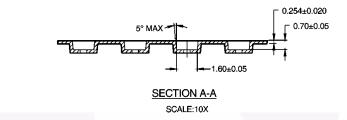
### Tape and Reel Specification (Continued)

### **Tape Format for MicroPak**

Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status
L6X	Leader (Start End)	125 (typ.)	Empty	Sealed
	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (typ.)	Empty	Sealed

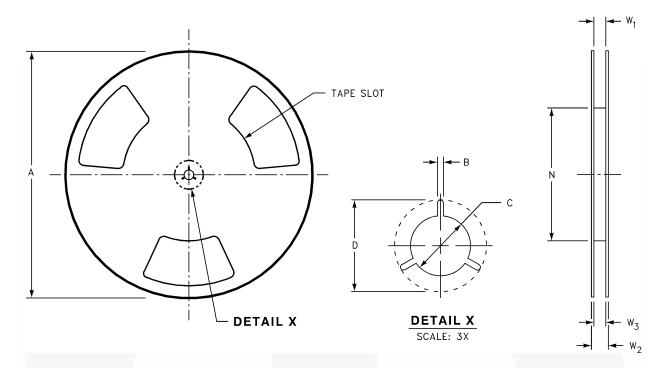
#### Tape Dimension millimeters





# Tape and Reel Specification (Continued)

Reel Dimension for MicroPak inches (millimeters)



Tape Size	Α	В	С	D	N		W <sub>1</sub>	W <sub>2</sub>	W <sub>3</sub>
8mm	7.0	0.059	0.512	0.795	2.165	0.33	1 +0.059/-0.000	0.567	W1 +0.078/-0.039
	(177.8)	(1.50)	(13.00)	(20.20)	(55.00)	(8.	40 +1.50/-0.00)	(14.40)	(W1 +2.00/-1.00)

### **Physical Dimensions**

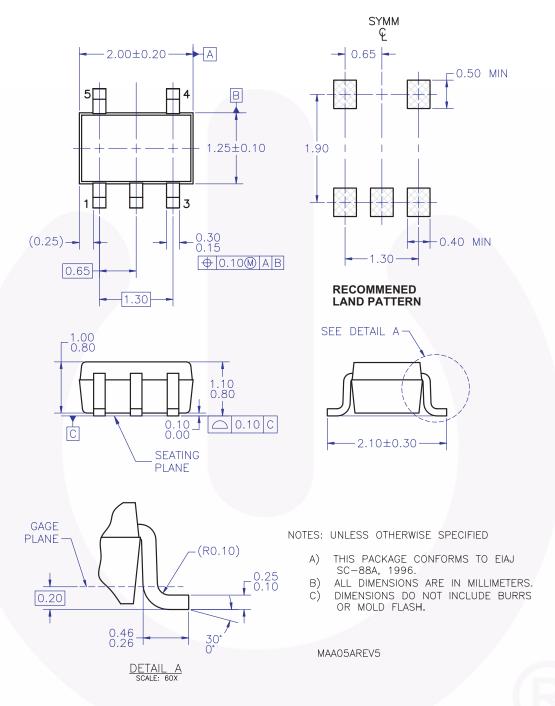
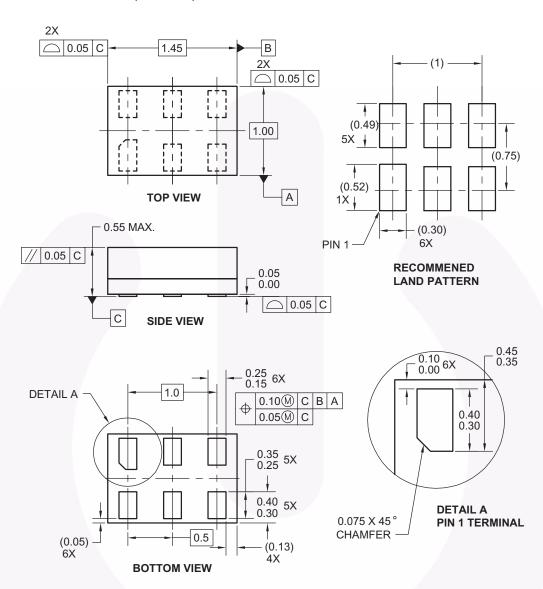


Figure 3. 5-Lead SC70, EIAJ SC-88a, 1.25mm Wide

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#### Physical Dimensions (Continued)



#### Notes:

- 1. CONFORMS TO JEDEC STANDARD M0-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-1994

MAC06AREVC

Figure 4. 6-Lead MicroPak, 1.0mm Wide

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- device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

#### PRODUCT STATUS DEFINITIONS

#### **Definition of Terms**

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	This datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. 134

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